

Serial No. 09/761,317
July 2, 2003
Reply to the Office Action dated April 2, 2003
Page 7 of 9

REMARKS/ARGUMENTS

Claims 1-20, 25, and 26 are pending in this application. By this Amendment, Applicants AMEND claims 1, 7, 13, and 17 and CANCEL claims 21-24.

The Examiner has indicated that the outstanding Office Action is a Final Office Action (paragraph no. 4 on page 4 of the Office Action). The Examiner is reminded "[b]efore [a] final rejection is in order[,] a **clear issue** should be developed between the examiner and applicant." MPEP § 706.07 (emphasis added).

It is the Applicants' understanding that the Examiner must consider the merits of each claim in each Office Action. However, the Examiner has failed to consider claims 21-26 which were added in the previous Amendment dated March 6, 2003. By this amendment, Applicants have amended claims 1, 7, 13, and 17 to include the feature recited in claims 21-24.

Accordingly, Applicants respectfully request reconsideration and withdrawal of the Finality of the outstanding Office Action and the consideration of claims 1, 7, 13, 17, 25, and 26.

Claims 1-20 were rejected under 35 U.S.C. § 103(a) as being unpatentable over Hirano et al. (U.S. 5,550,068) in view of Applicants' Admitted Prior Art (AAPA). Applicants respectfully traverse the rejection of claims 1-20.

Claim 1 has been amended to recite:

"A method of wiring formation comprising the steps of:
forming a feeder film partially on a substrate;
forming on the substrate a plating base film such that the plating
base film partially overlaps the feeder film;
forming a plated wiring on the plating base film; and
selectively removing at least a portion of the feeder film that is
exposed from the plated wiring; wherein
the plating base film includes a diffusion preventive layer."
(emphasis added)

Applicants' claim 1 recites the feature of "the plating base film includes a diffusion preventive layer." Applicants' claims 7, 13, and 17 recite features which are similar to

Serial No. 09/761,317

July 2, 2003

Reply to the Office Action dated April 2, 2003

Page 8 of 9

Applicants' claim 1, including the above emphasized feature. With the improved features of claim 1, Applicants have been able to provide a method of wiring formation wherein fine wiring is accurately formed by the semi-additive process using wet etching to remove the feeder film (see, for example, the second paragraph on page 3 of the Specification).

Applicants have amended claims 1, 7, 13, 17 to recite the feature "the plating base film comprises a diffusion preventive layer." As noted above, the Examiner has failed to address this feature.

First, Hirano et al. does not teach or suggest the feature of "the plating base film comprises a diffusion preventive layer" as recited in Applicants' claims 1, 7, 13, and 17.

Second, AAPA does not teach or suggest the feature of "the plating base film comprises a diffusion preventive layer" as recited in Applicants' claims 1, 7, 13, and 17.

In fact, neither Hirano et al. or AAPA teach or suggest anything at all about a plating base film which includes a diffusion preventive layer.

Accordingly, Applicants respectfully request reconsideration and withdrawal of the rejection of claims 1, 7, 13, and 17 under 35 U.S.C. §103(a) as being unpatentable over Hirano et al. in view of AAPA.

Accordingly, Applicants respectfully submit that Hirano et al. and AAPA, applied alone or in combination, fail to teach or suggest the unique combination and arrangement of elements recited in claims 1, 7, 13, and 17 of the present application. Claims 2-6, 25, and 26 depend upon claim 1 and are therefore allowable for at least the reasons that claim 1 is allowable. Claims 8-12 depend upon claim 7 and are therefore allowable for at least the reasons that claim 7 is allowable. Claims 14-16 depend upon claim 13 and are therefore allowable for at least the reasons that claim 13 is allowable. Claim 18-20 depend upon claim 17 and are therefore allowable for at least the reasons that claim 17 is allowable.

In view of the foregoing amendments and remarks, Applicants respectfully submit that this application is in condition for allowance. Favorable consideration and prompt

Serial No. 09/761,317

July 2, 2003

Reply to the Office Action dated April 2, 2003

Page 9 of 9

allowance are solicited.

The Commissioner is authorized to charge any shortage in fees due in connection with the filing of this paper, including extension of time fees, to Deposit Account No. 50-1353.

Respectfully submitted,

Date: July 2, 2003



Attorneys for Applicants

Joseph R. Keating
Registration No. 37,368

Christopher A. Bennett
Registration No. 46,710

KEATING & BENNETT LLP
10400 Eaton Place, Suite 312
Fairfax, VA 22030
Telephone: (703) 385-5200
Facsimile: (703) 385-5080